

ABSTRACT OF THE DISCLOSURE

SUBSTRATE PROCESSING APPARATUS AND
METHOD OF CONTROLLING THE SAME

A substrate processing apparatus is disclosed. In an embodiment, a substrate processing apparatus includes a plurality of polishing units including discharge valves that can discharge water at a predetermined flow rate, a plurality of cleaning units including discharge valves that discharges water at a predetermined flow rate, and a controller that controls opening and closing of the discharge valve of each of the plurality of polishing units and the plurality of cleaning units, and the controller controls opening and closing of the discharge valves of the plurality of polishing units and the plurality of cleaning units based on predetermined priority orders allocated to the plurality of polishing units and the plurality of cleaning units, so that the total discharge flow rate from the plurality of polishing units and the plurality of cleaning units is a predetermined flow rate or less.

Figure 1